N-Ch 100V Fast Switching MOSFETs

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

Green

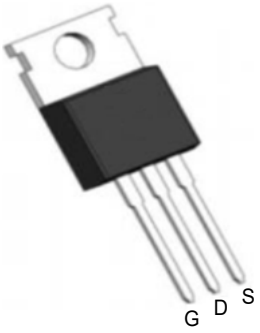
BVDSS	RDSON	ID
100V	25mΩ	40A

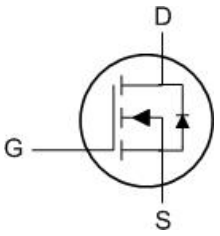
Description

The XR40N10T is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The XR40N10T meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO220AB Pin Configuration





Absolute Maximum Ratings (T_C=25℃ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		100	V
V_{GSS}	Gate-Source Voltage		±20	V
I_D	Continuous Drain Current	T_C = 25℃	40	A
		T_C = 100℃	21	A
I_{DM}	Pulsed Drain Current note1		120	A
EAS	Single Pulsed Avalanche Energy note2		30	mJ
P_D	Power Dissipation	T_C = 25℃	42	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		3.6	℃/W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	℃

Electrical Characteristics (T_J=25℃ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250μA	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=100V, V_{GS}=0V,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS}=0V, V_{GS}=±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250μA	0.8	1.2	1.6	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note3	V_{GS}=10V, I_D=10A	-	25	32.5	mΩ
		V_{GS}=4.5V, I_D=6A	-	26	36	mΩ
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS}=25V, V_{GS}=0V, f=1.0MHz	-	1964	-	pF
C_{oss}	Output Capacitance		-	90	-	pF
C_{rss}	Reverse Transfer Capacitance		-	74	-	pF
Q_g	Total Gate Charge	V_{DS}=80V, I_D=20A, V_{GS}=4.5V	-	20	-	nC
Q_{gs}	Gate-Source Charge		-	3.1	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	14	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	V_{DS}=80V, I_D=20A, R_G=3.1Ω, V_{GS}=4.5V	-	11	-	ns
t_r	Turn-on Rise Time		-	91	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	40	-	ns
t_f	Turn-off Fall Time		-	71	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	40	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	120	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS}=0V, I_S=20A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I_F=20A, dI/dt=100A/μs	-	64	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	152	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : T_J=25℃,V_{DD}=50V,V_G=10V,L=0.5mH,Rg=25Ω,I_{AS}= 11A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

Figure1: Output Characteristics

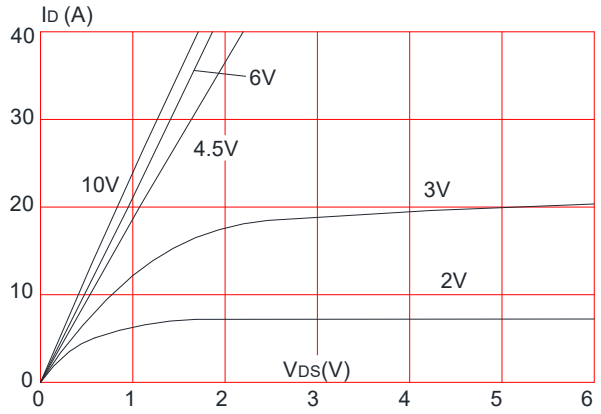


Figure 2: Typical Transfer Characteristics

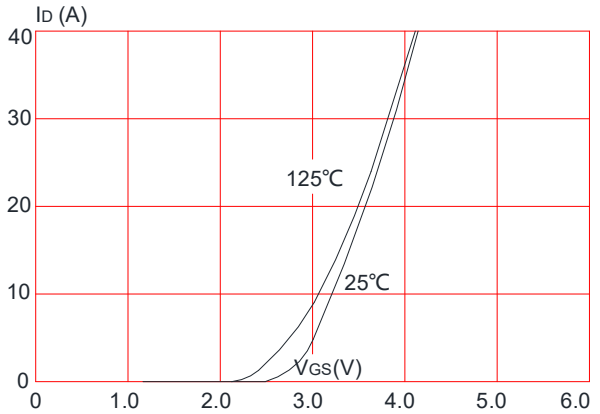


Figure 3: On-resistance vs. Drain Current

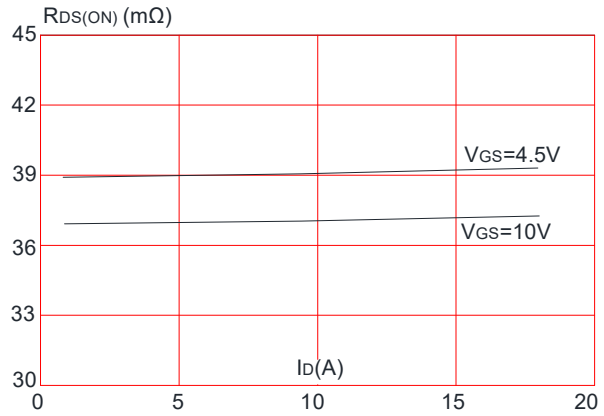


Figure 4: Body Diode Characteristics

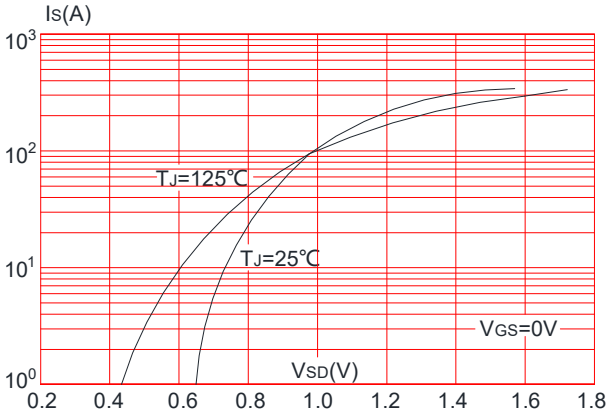


Figure 5: Gate Charge Characteristics

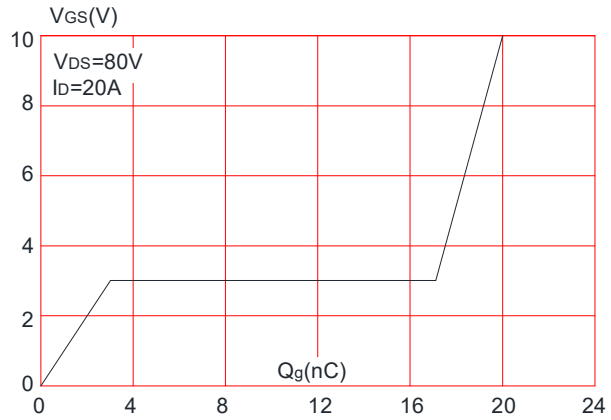


Figure 6: Capacitance Characteristics

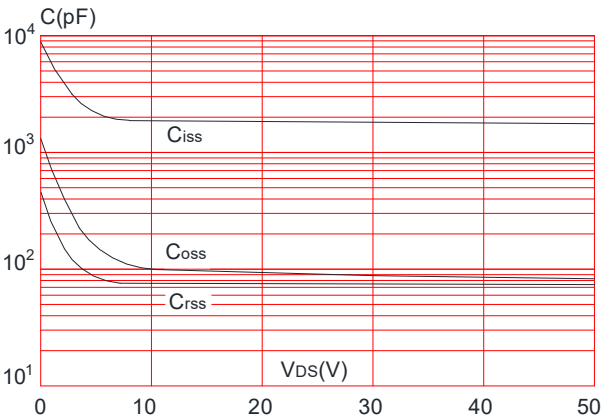


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

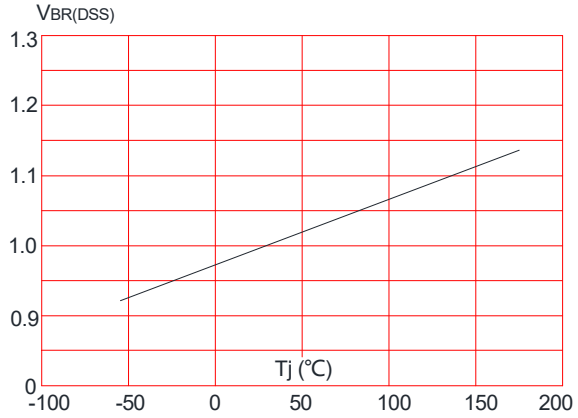


Figure 8: Normalized on Resistance vs. Junction Temperature

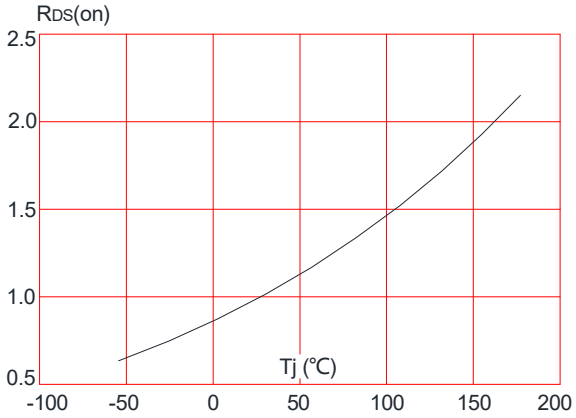


Figure 9: Maximum Safe Operating Area

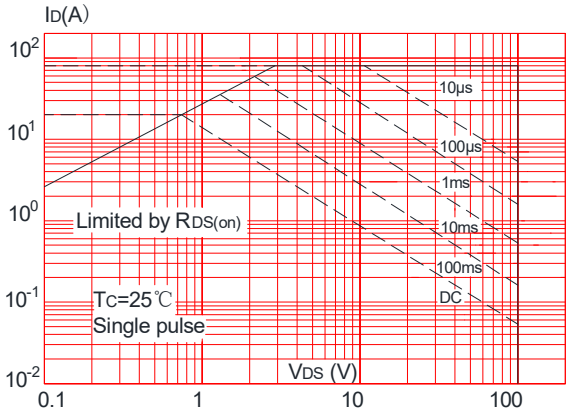


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

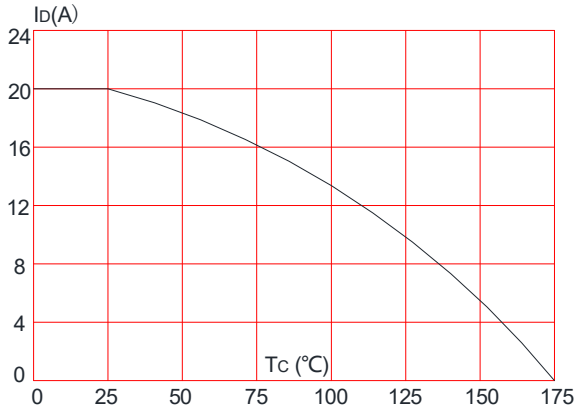
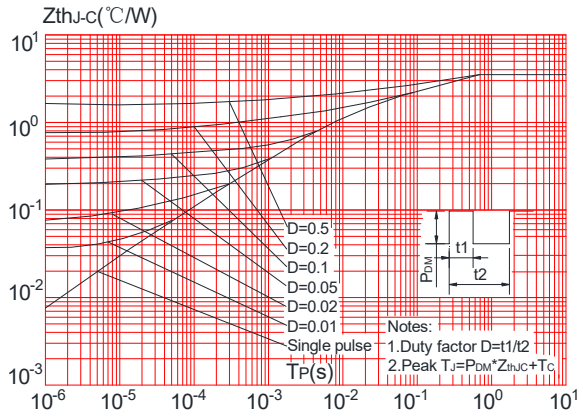
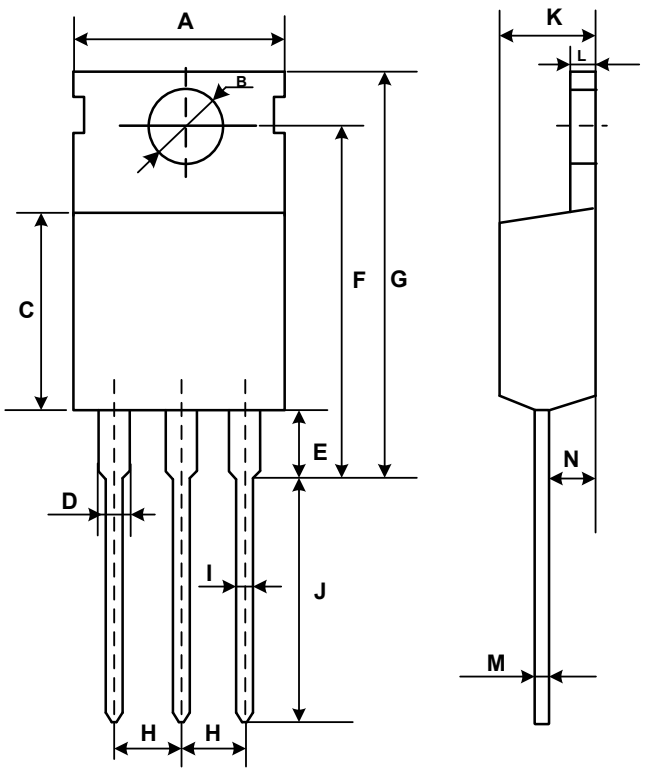


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



Mechanical Dimensions for TO-220



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SYMBOL	MM	
	MIN	MAX
A	9.70	10.30
B	3.40	3.80
C	8.80	9.40
D	1.17	1.47
E	2.60	3.50
F	15.10	16.70
G	19.55MAX	
H	2.54REF	
I	0.70	0.95
J	9.35	11.00
K	4.30	4.77
L	1.20	1.45
M	0.40	0.65
N	2.20	2.60